

FM27C010 1,048,576-Bit (128K x 8) High Speed CMOS EPROM

General Description

The FM27C010 is a High Performance 128K x 8 UV Erasable EPROM. It is manufactured using an advanced CMOS process technology enabling it to operate at speeds as fast as 25 ns Address Access Time (t_{ACC}). It was designed utilizing Fairchild's Alternate Metal Virtual Ground (AMG) cell. This innovative memory architecture results in a very high performance EPROM.

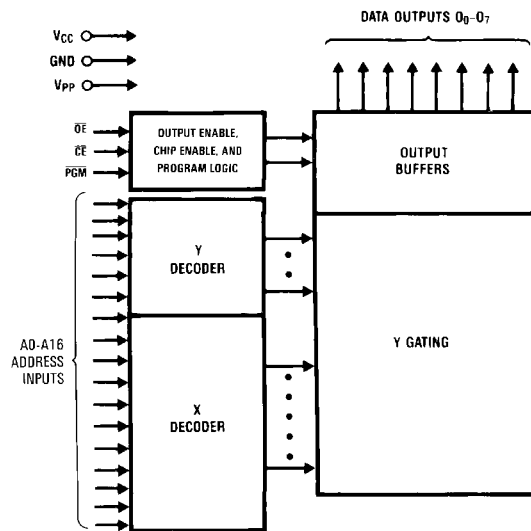
This product, with its high speed capability and high storage capacity is particularly appropriate for use with today's fast DSP processors and high-clock-rate microprocessors. In most mcases the SPU can operate without wait states. The FM27C010 is also designed for use in modem applications. It is an ideal memory for the newest modem chip sets.

The FM27C010 is available in the 600 Mil DIP, the surface mount PLCC and TSOP. Its standard JEDEC EPROM pinouts provide for an easy upgrade for current users of the NM27C010.

Features

- Fast Access Time
 - $t_{ACC} = 25$ ns
 - $t_{CE} = 25$ ns
- Immune to Latch-Up
 - Up to 200 mA
- Available in Popular Packages
 - CERDIP, PDIP, PLCC, TSOP

Block Diagram

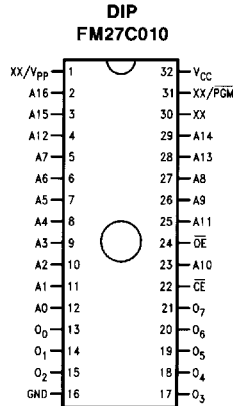


Product Selection Guide

Parameter	27C010-25	27C010-35	27C010-45	27C010-55
Address Access Time (Max)	25 ns	35 ns	45 ns	55 ns
Chip Select Time (Max)	25 ns	35 ns	45 ns	55 ns
Output Enable Time (Max)	12 ns	15 ns	20 ns	25 ns

Connection Diagram

27C040	27C020	27C512	27C256
XX/V _{pp}	XX/V _{pp}		
A16	A16		
A15	A15	A15	V _{pp}
A12	A12	A12	A12
A7	A7	A7	A7
A6	A6	A6	A6
A5	A5	A5	A5
A4	A4	A4	A4
A3	A3	A3	A3
A2	A2	A2	A2
A1	A1	A1	A1
A0	A0	A0	A0
O ₀	O ₀	O ₀	O ₀
O ₁	O ₁	O ₁	O ₁
O ₂	O ₂	O ₂	O ₂
GND	GND	GND	GND



27C256	27C512	27C020	27C040
		V _{CC}	V _{CC}
V _{CC}	V _{CC}	XX/PGM	A18
A14	A14	A17	A17
A13	A13	A14	A14
A8	A8	A13	A13
A9	A9	A8	A8
A11	A11	A9	A9
OE	OE	A11	A11
A10	A10	OE	OE
CE	CE	A10	A10
O ₇	O ₇	CE/PGM	A10
O ₆	O ₆		O ₇
O ₅	O ₅		O ₆
O ₄	O ₄		O ₅
O ₃	O ₃		O ₄

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Note: Compatible EPROM pin configurations are shown in the blocks adjacent to the FM27C010 pins.

Commercial Temp. Range (0°C to +70°C) V_{CC} = 5V ±10%

Parameter/Order Number	Access Time (ns)
FM27C010 Q, V, T 25	25
FM27C010 Q, V, T 35	35
FM27C010 Q, V, T 45	45
FM27C010 Q, V, T 55	55

Package Types: FM27C010 N, Q, V, T

N = Plastic DIP package

Q = Quartz-Windowed Ceramic DIP package

V = PLCC package

T = TSOP package

• All packages conform to the JEDEC standard.

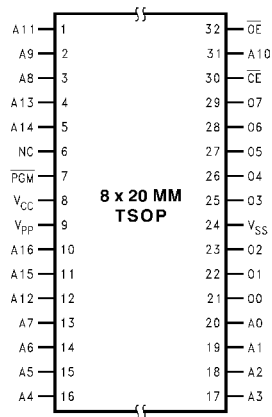
Extended Temp. Range (-40°C to +85°C) V_{CC} = 5V ±10%

Parameter/Order Number	Access Time (ns)
FM27C010 QE, VE, TE 45	45
FM27C010 QE, VE, TE 55	55

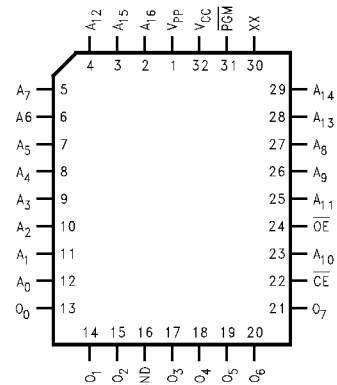
Pin Names

Symbol	Description
A0–A16	Addresses
CE	Chip Enable
OE	Output Enable
O0–O7	Outputs
PGM	Program
XX	Don't Care (during Read)

TSOP Pin Configuration



PLCC Pin Configuration



Top View

Absolute Maximum Ratings (Note 1)

Storage Temperature	-65°C to +125°C
All Input Voltages except A9 with Respect to Ground	-0.6V to +7V
V _{PP} and A ₉ with Respect to Ground	-0.6V to +14V
V _{CC} Supply Voltage with Respect to Ground	- 0.6V to +7V
ESD Protection	> 2000V

All Output Voltages with Respect to Ground V_{CC} + 1.0V to GND - 0.6V

Operating Range

Range	Temperature	V _{CC}	Tolerance
Commercial	0°C to +70°C	+5V	±10%
Industrial	-40°C to +85°C	+5V	±10%

Read Operation

DC Electrical Characteristics

(V_{CC} = 5.0 V ± 0.5 V)

Symbol	Parameter	Test Conditions	Min	Max	Units
V _{IL}	Input Low Voltage		-0.3	0.8	V
V _{IH}	Input High Voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 12 mA		0.45	V
V _{OH}	Output High Voltage	I _{OH} = -4 mA	2.4		V
I _{SB}	V _{CC} Standby Quiescent Current (CMOS)	$\overline{CE} \geq V_{CC} - 0.3 V$ All Pins $\geq V_{CC} - 0.3 V$ or $\leq 0.3 V$ (All Inputs Fixed, No Switching)	Comm'l	100	μA
			Industrial	150	μA
I _{CCSB0}	V _{CC} Standby Current (CMOS)	$\overline{CE} \geq V_{CC} - 0.3 V$ All Pins $\geq V_{CC} - 0.3 V$ or $\leq 0.3 V$ (Toggling) f ≤ 10 MHz	Comm'l	10	mA
			Industrial	15	mA
I _{CCSB1}	V _{CC} Standby Current (TTL)	$\overline{CE} \geq V_{IH}$ All Pins = V _{IH} or V _{IL} (Toggling) f ≤ 10 MHz	Comm'l	20	mA
			Industrial	25	mA
I _{CC1}	V _{CC} Active Current	$\overline{CE} = V_{IL}$ f ≤ 10 MHz I _{OUT} = 0 mA (Open Outputs)	Comm'l	25	mA
			Industrial	30	mA
I _{PP1}	V _{PP} Current During Read	$\overline{CE} = \overline{OE} = V_{IL}, V_{PP} = V_{CC}$		10	μA
I _{LI}	Input Leakage Current	0 V < V _{IN} < 5.5V	-10	10	μA
I _{LO}	Output Leakage Current	0 V < V _{OUT} < 5.5V	-10	10	μA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: I_{CC1} is tested with $\overline{OE} = V_{IH}$ to simulate open outputs.

Note 3: The FM27C010 device employs high speed output drivers, which can produce transient voltages at the device ground pin when discharging load capacitances through parasitic inductance between device ground and system ground. These transient voltages can result in significant reductions in measured input relay margins, particularly V_{IL}. Special care should be taken to minimize the inductance of the current path from device ground to system ground (by use of a ground plane or grid) and to eliminate ground loops, especially where multiple FM27C010 devices are used in a synchronous design.

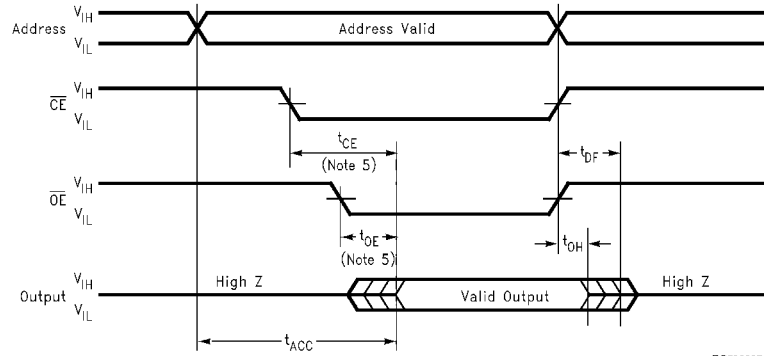
AC Read Characteristics

V_{CC} = 5.0 V ± 0.5 V, V_{PP} = V_{CC}

Symbol	Parameter	-25		-35		-45		-55		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACC}	Address to Output Delay		25		35		45		55	ns
t _{CE}	Chip Enable to Output Delay		25		35		45		55	ns
t _{OE}	Output Enable to Output Delay		12		15		20		25	ns
t _{DF}	Output Disable to Output Float (Note 4)		12		15		20		25	ns
t _{OH}	Output Hold	0		0		0		0		ns

Note 4: This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is not longer driven - see timing diagram.

AC Waveforms (Note 5)



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Note 5: \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} .

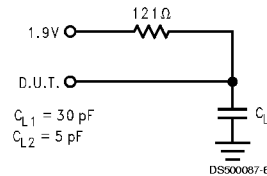
Capacitance (Note 6)

$T_A = +25^\circ\text{C}$, $f = 1\text{ MHz}$

Symbol	Parameter	Conditions	Typ (Note 6)	Max	Units
C_{IN}	Input Capacitance	$V_{IN} = 0\text{V}$	4	6	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0\text{V}$	8	12	pF
C_{VPP}	V_{PP} Capacitance	$V_{PP} = 0\text{V}$	18	25	pF

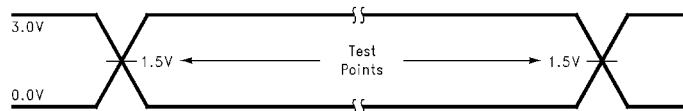
Note 6: Typical values are for $T_A = 25^\circ\text{C}$ and nominal supply voltages.

Test Load (High Impedance Test Systems)



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AC Testing Input/Output Waveform



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AC testing inputs are driven at 3.0 V for a logic "1" and 0.0 V for a logic "0." Timing measurements are made at 1.5 V for input and output transitions in both directions.

Note 7: Provide adequate decoupling capacitance as close as possible to this device to achieve the published AC and DC parameters. A 0.1 microfarad capacitor in parallel with a 0.01 microfarad capacitor connected between V_{CC} and ground is recommended. Inadequate decoupling may result in access time degradation or other transient performance failures.

DC Programming Characteristics (Note 8), (Note 9), and (Note 10)

($T_A = 25^\circ\text{C} \pm 5^\circ\text{C}$, $V_{CC} = 6.25 \pm 0.25\text{ V}$, $V_{PP} = 12.75 \pm 0.25\text{ V}$)

Symbol	Parameter	Min	Max	Units
I_{LI}	Input Capacitance	-10	10	μA
I_{PP}	Output Capacitance		60	mA
I_{CC}	V_{PP} Capacitance		50	mA
V_{OL}	Output Low Voltage During Verify ($I_{OL} = 12\text{ mA}$)		0.45	V
V_{OH}	Output High Voltage During Verify ($I_{OH} = -4\text{ mA}$)	2.4		V

Note 8: V_{CC} must be applied coincidentally or before V_{PP} and removed coincidentally or after V_{PP} .

Note 9: V_{PP} must not be greater than 13 volts including overshoot. During $\overline{\text{CE}} = \overline{\text{PGM}} = V_{IL}$, V_{PP} must not be switched from 5 volts to 12.75 volts or vice-versa.

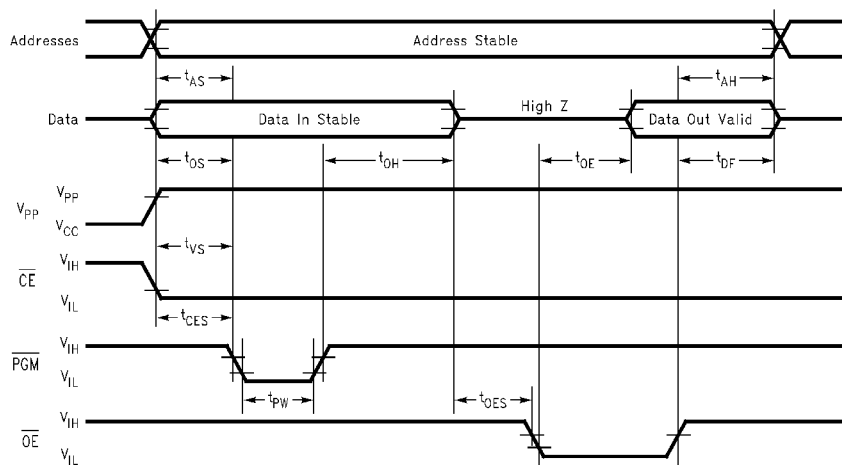
Note 10: During power up the $\overline{\text{PGM}}$ pin must be brought high ($\geq V_{IH}$) either coincident with or before power is applied to V_{PP} .

AC Programming Characteristics

($T_A = 25^\circ\text{C} \pm 5^\circ\text{C}$, $V_{CC} = 6.25 \pm 0.25\text{ V}$, $V_{PP} = 12.75 \pm 0.25\text{ V}$)

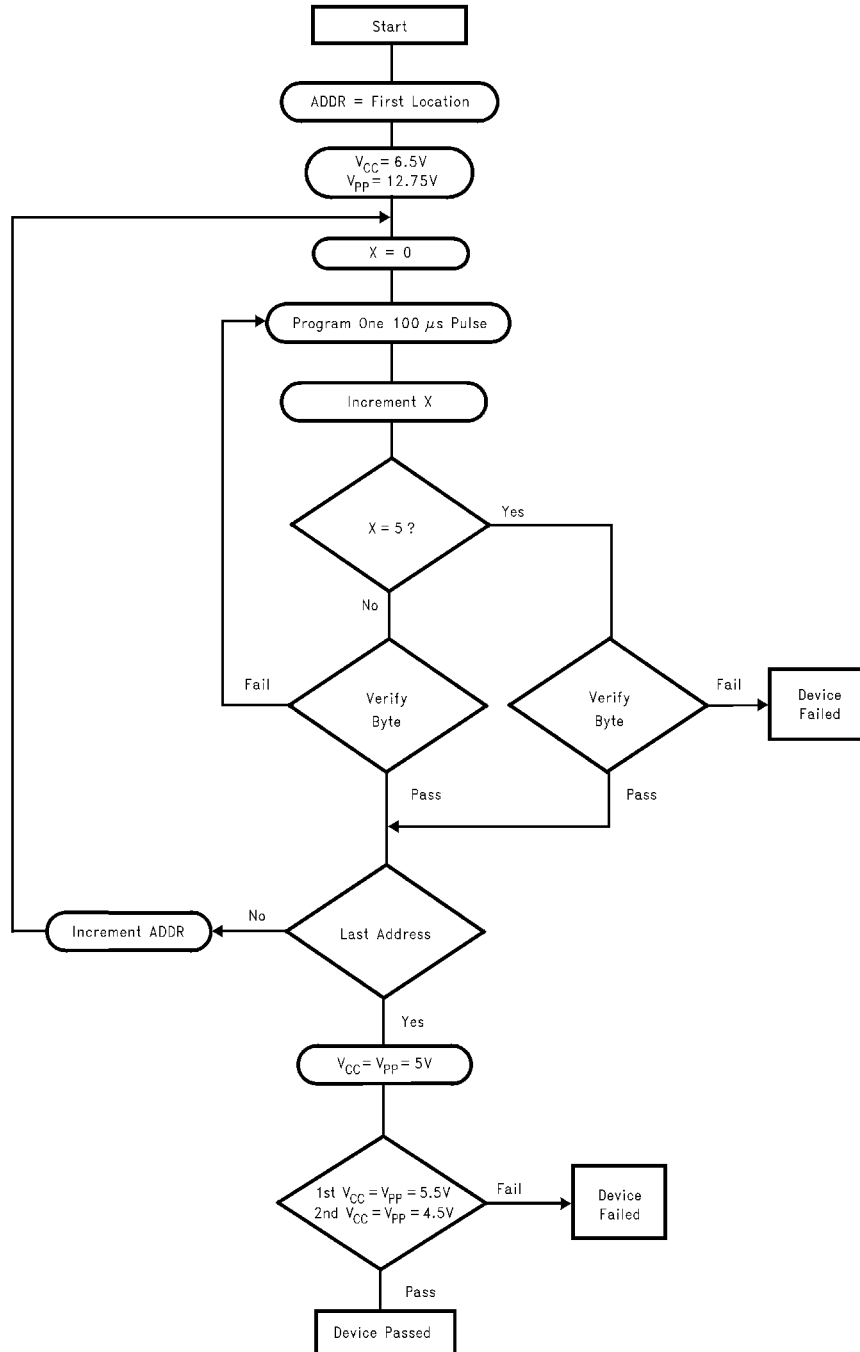
Symbol	Parameter	Min	Typ	Max	Units
t_{AS}	Address Setup Time	2			μs
t_{OES}	Output Enable Setup Time	2			μs
t_{OS}	Data Setup Time	2			μs
t_{AH}	Address Hold Time	0			μs
t_{OH}	Data Hold Time	2			μs
t_{DF}	Chip Disable to Output Float Delay	0		55	ns
t_{OE}	Data Valid from Output Enable			55	ns
t_{VS}/t_{CES}	V_{PP} Setup Time/ $\overline{\text{CE}}$ Setup Time	2			μs
t_{PW}	$\overline{\text{PGM}}$ Pulse Width	0.1		1	ms

Programming Waveform



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Fast Programming Algorithm



Note: Turbo Programming Algorithm will be available in Quarter 1, 1998 - Please check with Factory.

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Mode Selection

The modes of operation of FM27C010 listed below. A single 5V power supply is required in the read mode. All inputs are TTL levels except for V_{PP} and A_9 for device signature.

TABLE 1. Modes Selection

Mode	Pins	\overline{CE}	\overline{OE}	\overline{PGM}	A_9	A_0	V_{PP}	V_{CC}	Outputs
Read		V_{IL}	V_{IL}	X (Note 11)	X	X	X	5.0 V	D_{OUT}
Output Disable		X	V_{IH}	X	X	X	X	5.0 V	High Z
Standby		V_{IH}	X	X	X	X	X	5.0 V	High Z
Program		V_{IL}	V_{IH}	V_{IL}	X	X	V_{PP} (Note 12)	6.25 V	D_{IN}
Program Verify		V_{IL}	V_{IL}	V_{IH}	X	X	V_{PP} (Note 12)	6.25 V	D_{OUT}
Program Inhibit		V_{IH}	X	X	X	X	V_{PP} (Note 12)	5.0 V	High Z
Manufacturer Signature (Note 13)		V_{IL}	V_{IL}	X	V_{IH} (Note 12)	V_{IL}	X	5.0 V	23 H
Device Signature (Note 13)		V_{IL}	V_{IL}	X	V_{IH} (Note 12)	V_{IH}	X	5.0 V	F8 H

Note 11: X can be V_{IL} or V_{IH} .

Note 12: $V_{IH} = V_{PP} = 12.75 \pm 0.25$ V.

Note 13: $A_1 - A_8, A_{10} - A_{14} = V_{IL}$.

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